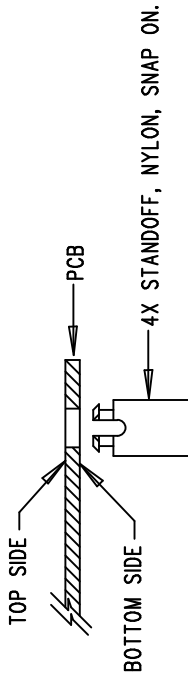



1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE; REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS AT 4 LOCATIONS AS SHOWN BELOW:



APPROVALS		 <b>LINEAR TECHNOLOGY</b>		1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1800 <a href="http://www.linear.com">www.linear.com</a> LTC CONFIDENTIAL - FOR CUSTOMER USE ONLY	
PCB DES.	HZ	<b>TITLE: TOP ASSEMBLY DRAWING®</b> 10A STEP-DOWN $\mu$ MODULE REGULATOR WITH INPUT AND OUTPUT OVP			
APP ENG.	YAN L.				
		SIZE	IC NO.	LTM4641EV	REV.
		N/A		DEMO CIRCUIT	2
SCALE = NONE		FILENAME: DC1543A-2.PCB			SHT 1 OF 2